

Specific questions exemption 11

“Lead used in compliant pin connector systems”

The following specific questions should be answered in your stakeholder contribution if you support exemption 11 to be continued / amended / discontinued:

1. Please state the **amount of lead** used per application, the lead content in the homogeneous material, the annual production volume as well as the number of applications related to exemption no. 11 put on the EU market annually.
2. Please **justify** why this exemption is still necessary. Previous related exemption requests for fine pitch connectors, flexible flat cables etc. were not granted during the last evaluation in 2006 since one of the stakeholders withdrew his request stating that he will accept gold as a viable alternative for the time being. Explain and justify why e.g. gold is not a **viable substitute**.
3. Besides a possible gold alternative, more knowledge is available on whisker generation and mitigation mechanisms that can avoid whiskers (post-bake of components after finishing, layers under the tin to mitigate whisker growth...). What has changed since the last evaluation in 2004 and where is **substitution** now technically feasible?
4. Results of the previous evaluation in 2004 state that a reflow or wave soldering process heating up the coated pins would reduce the **whisker risk**. Why can the pins not be heated up simulating a soldering process in order to mitigate the whisker risk? This approach would also be compliant with a post-bake treatment of copper-based components to mitigate the whisker risk.
5. Assuming the current exemption will be given an **expiry date**, what date do you think is technologically feasible for industry?